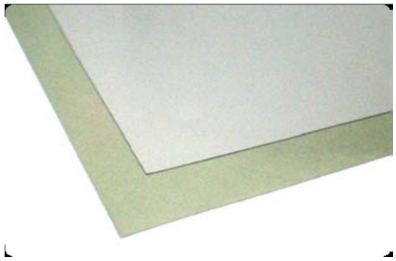
Thin Silicone Thermal Pad MPN Series



AMEC Thermasol MPN series of thermal filler pads are extremely thin yet with 5W/mk high thermal conductivity. Its soft characteristic also provides cushioning and excellent gap-filling properties. Can be supplied in sheets, rolls and custom die cut shapes.

Features

- 5W/mk High thermal conductivity
- Conformable, low hardness
- Electrically Isolating
- High breakdown voltage
- 0.25mm ultra-thin

Applications

- CPU, GPU (Notebooks, Desktops, Servers)
- Memory
- Display (LED, LCD, PDP etc)
- Custom ASICS Chips
- LED Applications
- Digital Mobile
- Telecommunication Equipment

Item	Unit	Value	Standard
Thermal Conductivity	W/mK	5	ASTM D5470
Thermal Impedance	$^{o}C.in^{2}/W$	0.25mm – 0.08 0.5mm - 0.13 1.0mm- 0.29	ASTM D5470
Thickness	mm	0.25,0.5,1.0	
Hardness	Shore 00	40~80	ASTM D2240
Breakdown Voltage	kV	5.8	ASTM D149
Volume Resistance	Ω.cm	$6.1x10^{11}$	ASTM D257
Density	g/cm^{3}	3.0	ASTM D792
Flammability rating	-	94 V-0	UL
Operating Temperature	˚C	-40~150	-
ROHS	-	Non detected	-

Part Numbers system –

Series – Thermal Conductivity /Shore Hardness-Sheet size

E.g.: MPN-5040-150x300x0.25

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